

Application Serial No. 10/023,940
Response dated July 23, 2004
Reply to Office action mailed April 27, 2004

Amendments to the Specification:

Replace the first full paragraph at page 7, spanning lines 4-12, of the specification of record with the following replacement paragraph. No new matter has been added.

The ozone generator 4 5 is connected to the cleaning bath 1 besides the mixing tank 2. Thus, in the early cleaning process, ozone is supplied only to the mixing tank 2. However, after the supply of the cleaning solution into the cleaning bath 1 is completed, the supply of ozone into the mixture tank 2 stops and ozone is supplied only into the cleaning bath 1. As described above, the semiconductor cleaning apparatus is designed to maximize the contaminant removal efficiency on the semiconductor wafer surface by complementing the amount of ozone consumed during the cleaning process to uniformly maintain the concentration of ozone in the cleaning solution.